

1.5A SURFACE MOUNT GLASS PASSIVATED RECTIFIER

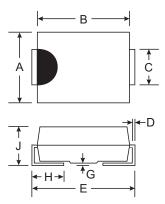
Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop and High Current Capability
- Surge Overload Rating to 50A Peak
- Ideally Suited for Automated Assembly
- Lead Free Finish/RoHS Compliant (Note 3)

Mechanical Data

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number, See Page 2
- Ordering Information: See Page 2
- Approx. Weight: SMA 0.064 grams

SMB 0.093 grams



Dim	SN	/ΙΑ	SMB			
	Min	Max	Min	Max		
Α	2.29	2.92	3.30	3.94		
В	4.00	4.60	4.06	4.57		
С	1.27	1.63	1.96	2.21		
D	0.15	0.31	0.15	0.31		
Е	4.80	5.59	5.00	5.59		
G	0.10	0.20	0.10	0.20		
Н	0.76	1.52	0.76	1.52		
J	2.01	2.62	2.00	2.62		
All Dimensions in mm						

A Suffix Designates SMA Package No Suffix Designates SMB Package

@T_A = 25°C unless otherwise specified

Maximum Ratings and Electrical Characteristics

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	S2 A/AA	S2 B/BA	S2 D/DA	S2 G/GA	S2 J/JA	S2 K/KA	S2 M/MA	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		50	100	200	400	600	800	1000	٧
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T _T = 100°C		1.5						Α	
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)		50					Α		
Forward Voltage @ I _F :	= 1.5A V _{FM}	1.15					V		
$ \begin{array}{llllllllllllllllllllllllllllllllllll$		5.0 125					μΑ		
Typical Total Capacitance (Note 1)		20						pF	
Typical Thermal Resistance, Junction to Terminal (Note 2)		20					°C/W		
Operating and Storage Temperature Range		-65 to +150							°C

Notes:

- 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
- 2. Thermal Resistance Junction to Terminal, unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.
- 3. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.



Ordering Information (Note 4)

Device*	Packaging	Shipping
S2xA-13-F	SMA	5000/Tape & Reel
S2x-13-F	SMB	3000/Tape & Reel

^{*} x = Device type, e.g. S2AA-13-F (SMA package); S2A-13-F (SMB package).

4. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



XXX = Product type marking code, ex: S2A (SMB package) XXXX = Product type marking code, ex: S2AA (SMA package)

);; = Manufacturers' code marking YWW = Date code marking Y = Last digit of year ex: ž for 2002 WW = Week code 01 to 52

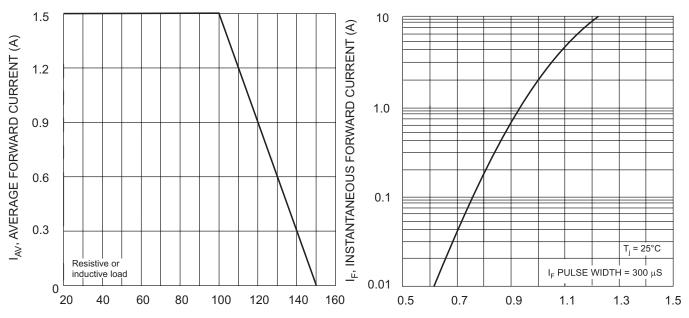


Fig. 1 Forward Current Derating Curve 60 I_{FSM}, PEAK FORWARD SURGE CURRENT (A) Single Half-Sine-Wave INSTANTANEOUS REVERSE CURRENT (µA) JEDEC Method 50 40 30 20

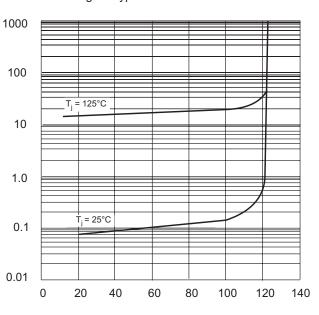
10

0

1

T_T, TERMINAL TEMPERATURE (°C)

V_E, INSTANTANEOUS FORWARD VOLTAGE (V) Fig. 2 Typical Forward Characteristics



NUMBER OF CYCLES AT 60 Hz Fig. 3 Forward Surge Current Derating Curve

10

PERCENT OF RATED PEAK REVERSE VOLTAGE (%) Fig. 4 Typical Reverse Characteristics

DS16004 Rev. 10 - 2 2 of 3 S2A/A - S2M/A

100



IMPORTANT NOTICE

Diodes, Inc. and its subsidiaries reserve the right to make changes without further notice to any product herein to make corrections, modifications, enhancements, improvements, or other changes. Diodes, Inc. does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others. The user of products in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on our website, harmless against all damages.

LIFE SUPPORT

The products located on our website at **www.diodes.com** are not recommended for use in life support systems where a failure or malfunction of the component may directly threaten life or cause injury without the express written approval of Diodes Incorporated.